

Docket No.: 1081.1102

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Masatoshi AKAGAWA

Serial No. 09/754,323

Confirmation No. 3680

Filed: January 5, 2001

Examiner: Scott A. Brairton

Group Art Unit: 2823

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR

LETTER TO THE EXAMINER REQUESTING APPROVAL OF THE CHANGES TO THE DRAWINGS

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

For:

It is respectfully requested that the Examiner having jurisdiction over the subject application approve the amendments to the drawings as indicated in RED on the attached copy of Figures 1A-D.

Respectfully submitted,

STAAS & HALSEY LLP

Date: <u>Sept 18 2002</u>

By:

Patrick J. Stanzione Registration No. 40,434

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CERTIFICATE UNDER 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231

on September 18,2002 STAAS & HALSEY, 12 11:00

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Statember 18, 2002

Docket No.: 1081.110 THE UNITED STATES PATENT AND TRADEMARK OFFICE In rethe Application of: Masatoshi AKAGAWA Serial No. 09/754,323 Group Art Unit: 2823 Confirmation No. 3680 Filed: January 5, 2001 Examiner: Scott A. Brairton SEMICONDUCTOR DEVICE AND MANUFACTURING THE THORSE TO SER 1.8(a) For: I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner **AMENDMENT** of Patents and Trademarks, Washington, D.C. 20231 **Assistant Commissioner for Patents** Washington, D.C. 20231 Sir: This is in response to the Office Action mailed June 18, 2002, and having a period for response set to expire on September 18, 2002. The following amendments and remarks are respectfully submitted. Reconsideration of the claims is respectfully requested. IN THE CLAIMS: Please AMEND the following claims:

1.) (ONCE AMENDED) A semiconductor device comprising:

plural pairs of conductor layers having wiring patterns and an insulating layer located thereon; wherein:

a semiconductor element is imbedded inside said insulating layer;

the <u>semiconductor element</u> is <u>electrically connected to a wiring pattern of said conductor</u>

a wiring pattern of said conductor layer is electrically connected, by via holes, to a wiring pattern of the conductor layer of a different pair of a conductor layer having wiring patterns and an insulating layer located thereon.

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layer; and

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